

Statement of Compliance

Requested Part

TE Internal Number:1-825433-5Product Description:MOD 2 PINHDR 1X15P.Part Status:ActiveMil-Spec Certified:NoEU ROHS Directive 2011/65/EUCompliantThis declaration covers EU Directive 2011/65/EU incl. Delegated Directive 2015/63/EUCompliantChina RoHS 2 Directive:Compliant2000/53/ECON Restricted Materials Above Threshold MIIT Order No 32, 2016EU REACH Regulation (EC) No. 1907/2006Current ECHA Candidate List: JAN 2023 (233) Candidate List Declared Against: JAN 2023 (233) Does not contain REACH SVHCKaterial Declaration:MD_1-825433-5 MD_1-825433-5	11 June 2023	1-82543	33-5 (Part 1 d	of 1)	
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MD 1-825433-5		Material Declarations:	MD_1-825433-5		
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TE Connectivity Corporation

1050 Westlakes Drive

Berwyn, PA 19312

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change.

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked.

Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV).

Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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